





DMNH6008SCT

N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	Rds(on) max	I _{D MAX} T _C = +25°C	
60V	$8.0 \text{m}\Omega @ V_{GS} = 10V$	130A	

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}), yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

Applications

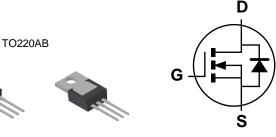
- Motor Control
- Backlighting
- DC-DC Converters
- Power Management Functions

Features

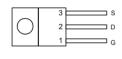
- Rated to +175°C—Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching—Ensures More Reliable and Robust End Application
- Low Input Capacitance
- Low Input/Output Leakage
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- An Automotive-Compliant Part is Available Under Separate Datasheet (<u>DMNH6008SCTQ</u>)

Mechanical Data

- Case: TO220AB
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Terminals: Matte Tin Finish Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 ³
- Terminal Connections: See Diagram Below
- Weight: 1.85 grams (Approximate)







Top View Pin Out Configuration

Ordering Information (Note 4)

Top View

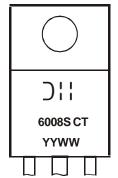
Bottom View

Part Number	Case	Packaging	
DMNH6008SCT	TO220AB	50 Pieces/Tube	

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



O'll = Manufacturer's Marking 6008SCT = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 18 = 2018) WW = Week (01 to 53)



Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	60	V
Gate-Source Voltage			V_{GSS}	20	V
Continuous Drain Current (Note 5) V _{GS} = 10V	Steady State	$T_{C} = +25^{\circ}C$ $T_{C} = +100^{\circ}C$	I _D	130 90	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	200	Α
Maximum Continuous Body Diode Forward Current (Note 5)			Is	80	Α
Avalanche Current (Note 6) L=0.1mH			I _{AS}	62	Α
Avalanche Energy (Note 6) L=0.1mH			E _{AS}	190	mJ

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5) $T_C = +25^{\circ}C$ $T_C = +100^{\circ}C$	P _D	210 100	W
Thermal Resistance, Junction to Case (Note 5)	R _{eJC}	0.7	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +175	°C

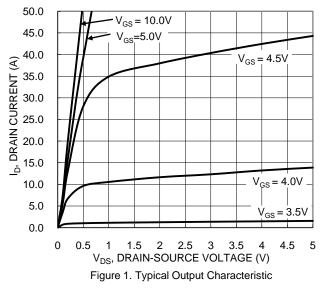
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

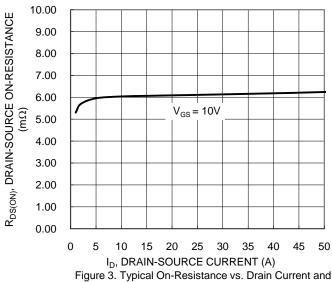
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	60		_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_		1	μΑ	$V_{DS} = 48V$, $V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	2		4	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	6.0	8.0	mΩ	$V_{GS} = 10V, I_D = 20A$	
Diode Forward Voltage	V_{SD}	_	0.7	1.2	V	$V_{GS} = 0V$, $I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	_	2,596	_		V _{DS} = 30V, V _{GS} = 0V f = 1.0MHz	
Output Capacitance	Coss	_	437	_	pF		
Reverse Transfer Capacitance	C _{rss}	_	118	_			
Gate Resistance	Rg	_	2.0	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V _{GS} = 10V)	Q_g		40	_		$V_{DD} = 30V, I_D = 20A$	
Total Gate Charge (V _{GS} = 4.5V)	Q_g	_	21	_	nC		
Gate-Source Charge	Q_{gs}		8.3	_	IIC		
Gate-Drain Charge	Q_{gd}	_	11.8	_			
Turn-On Delay Time	t _{D(ON)}	_	5.7	_		$V_{DD} = 30V, V_{GS} = 10V,$ $R_g = 1\Omega, I_D = 20A$	
Turn-On Rise Time	t _R	_	5.0	_	20		
Turn-Off Delay Time	t _{D(OFF)}	_	15.6	_	ns		
Turn-Off Fall Time	t _F	_	3.4	_			
Reverse Recovery Time	t _{RR}	_	33	_	ns	1 200 di/dt 1000///	
Reverse Recovery Charge	Q _{RR}	_	33	_	nC	$I_F = 20A$, di/dt = 100A/ μ s	

Notes:

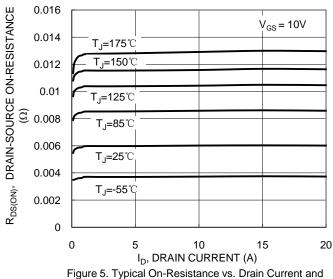
- 5. Device mounted on an infinite heatsink.
- 5. Las and Eas ratings are based on low frequency and duty cycles to keep T_J = +25°C.
 7. Short duration pulse test used to minimize self-heating effect.
 8. Guaranteed by design. Not subject to product testing.

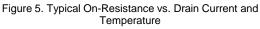






Gate Voltage





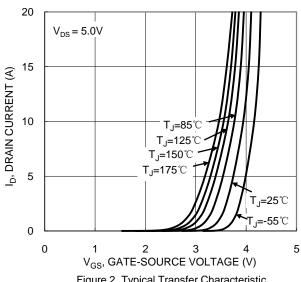


Figure 2. Typical Transfer Characteristic

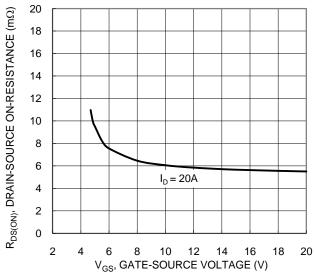


Figure 4. Typical Transfer Characteristic

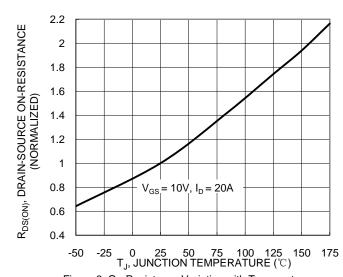


Figure 6. On-Resistance Variation with Temperature





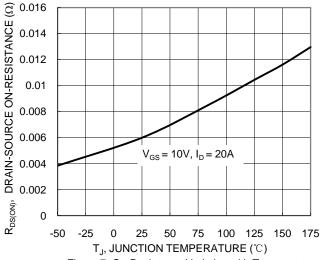


Figure 7. On-Resistance Variation with Temperature

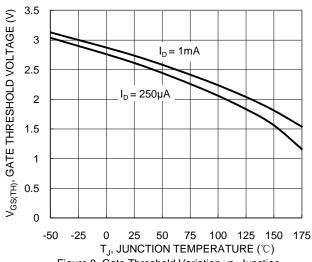


Figure 8. Gate Threshold Variation vs. Junction Temperature

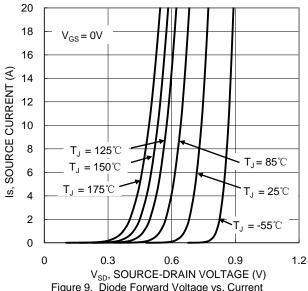
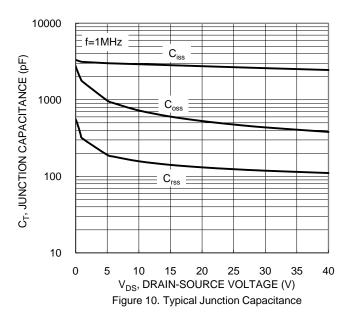
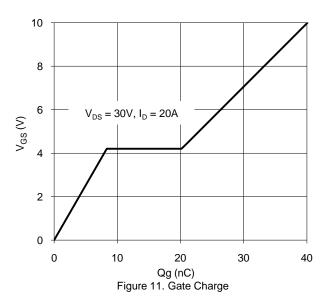
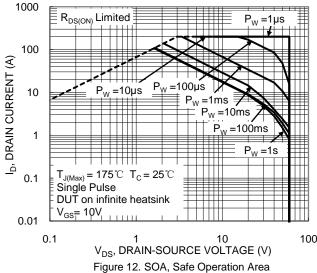


Figure 9. Diode Forward Voltage vs. Current









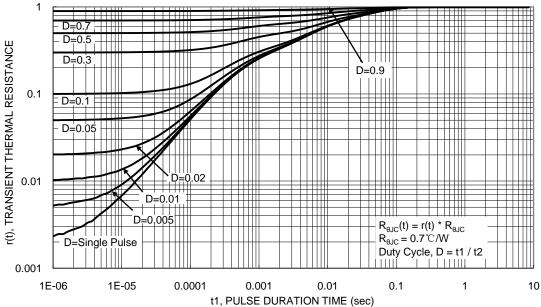


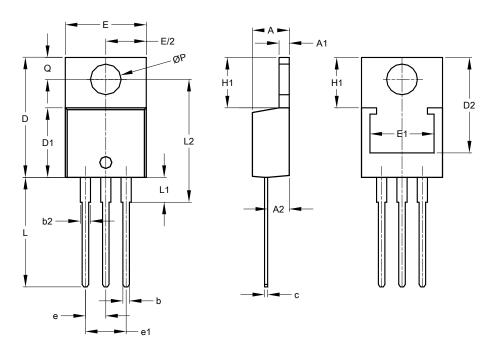
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO220AB



TO220AB					
Dim	Min	Max	Тур		
Α	3.56	4.82	_		
A1	0.51	1.39	_		
A2	2.04	2.92	_		
b	0.39	1.01	0.81		
b2	1.15	1.77	1.24		
C	0.356	0.61	_		
D	14.22	16.51	_		
D1	8.39	9.01	_		
D2	11.45	12.87	_		
е			2.54		
e1	_	_	5.08		
Е	9.66	10.66	_		
E1	6.86	8.89	_		
H1	5.85	6.85	_		
L	12.70	14.73	_		
L1	_	4.42	_		
L2	15.80	17.51	16.00		
Р	3.54	4.08	_		
ø	2.54	3.42	_		
All Dimensions in mm					



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